

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

Additions to claims are underlined and deletions from claims are presented in ~~striketrough~~ text.

26. An RFID device comprising:  
a first electrical component having  
a first electrically conductive contact;  
a second electrical component having  
a second electrically conductive contact;  
wherein the first and second electrically conductive contacts are in alignment  
with one another;  
at least one electrically conductive hard particle attached to at least one of the first and  
second electrically conductive contacts,  
wherein the at least one electrically conductive hard particle has a hardness at  
least as great as that of at least one of the first and second electrically conductive contacts;  
a non-conductive adhesive disposed between the first and second electrically  
conductive contacts;  
wherein the first and second electrically conductive contacts are held together by the  
non-conductive adhesive once the adhesive cures;  
wherein a permanent electrical connection is formed between the first and second  
electrically conductive contacts; and  
wherein a permanent physical attachment is formed between the first electrical  
component and the second electrical component.

59. The method of claim ~~47~~ 49 or 57, wherein the at least one electrically  
conductive hard particle is attached to the first electrically conductive contact by an  
electroless metal-particle co-deposition process.

71. The electrical component of claim 70, wherein the chip further comprises at  
least one of the following: a discrete circuit device, an integrated circuit device, a memory  
device, a microprocessor device, a transceiver device, and an electro-optic device.